

## Materials Declaration

<b>Package</b>	SOIC
<b>Body Size</b>	300 mils
<b>LeadCount</b>	28
<b>Option</b>	Pb Free

### Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	5.26 E-02	66907
SiO2 Filler	85	4.47 E-01	568714
Phenol Resin	3	1.58 E-02	20072
Antimony_Sb2O3	1.5	7.89 E-03	10036
Brominated Resin	0.5	2.63 E-03	3345

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.15 E-01	272841
Fe	2.35	5.17 E-03	6576
P	0.03	6.60 E-05	84
Zn	0.12	2.64 E-04	336

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.92 E-03	2437

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.98 E-03	6.33 E+03

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.19 E-03	1513

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.97 E-02	37806

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.90 E-04	750
Ag Filler	75	1.77 E-03	2250

### Package Totals

Weight (g)	PPM
7.87 E-01	1000000

### Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

### Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



ADI Proprietary

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### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.92 E-03	2437

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.23 E-03	5382
Pb	15	7.47 E-04	950

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.19 E-03	1513

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.97 E-02	37806

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
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Ag Filler	75	1.77 E-03	2250

### Package Totals

Weight (g)	PPM
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